

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY. (HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED OVER ALL. (HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED ALL AREA. (HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A"). HIGH PERFORMANCE MATERIAL FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")

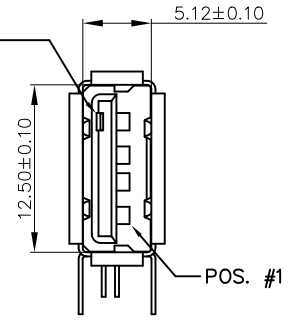
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

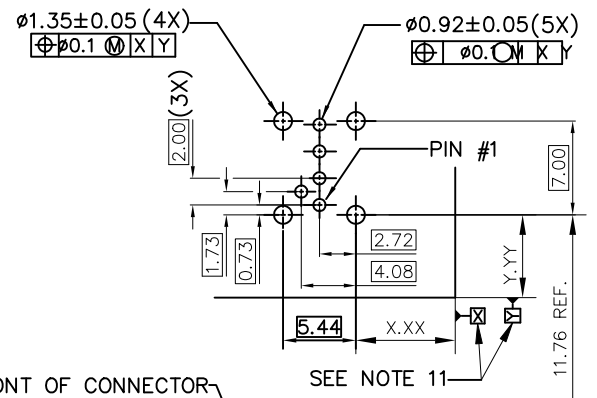
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

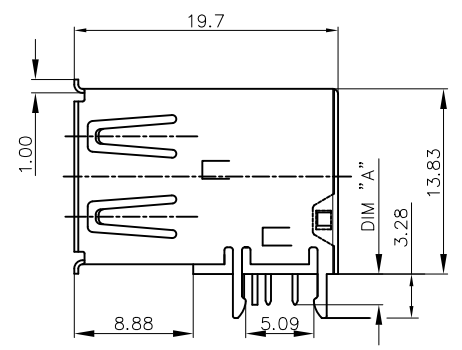


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM) IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
SHIELD: 1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF; 73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS (TO BE CONTINUED)

mat'l. code				surface123/tolerance			projection	product family		
ltr	ecn no	dr	date	ISO 1302	ISO 406	ISO 1101		HPL 511 USB 2.0		
AJ	ELX-N-27708	LZ	2017/08/15	tolerances unless otherwise specified				title		
				angles	linear					
AD	ELX-N-012006	A.ZH	06/25/2012	0±2°			scale 1:1	USB UP-RIGHT RECEPT		
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97	Amphenol FCI	dwg no sheet 1 of 4 size		
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97				
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97				
AH	ELX-N-21919	LQ	08/04/2015	appd	JENN TSAO	5/20/97				
sheet	revision							type Product Customer Drawing		
index	sheet									

PRODUCT NO.
73725

(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

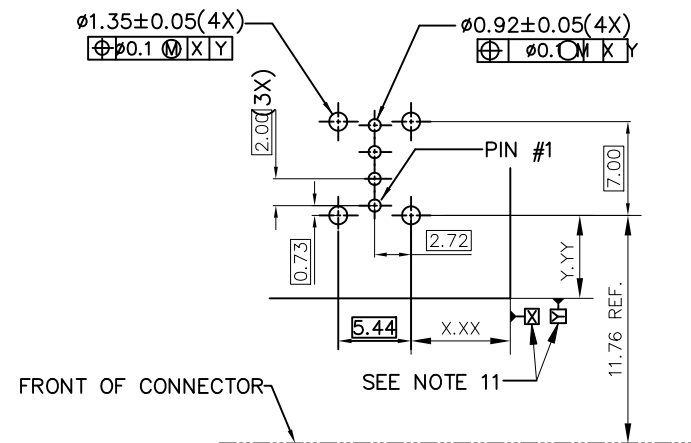
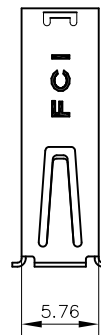
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

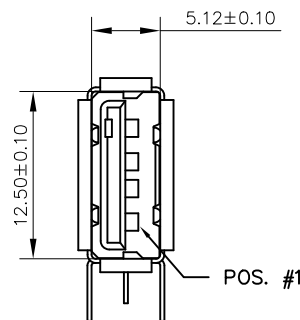
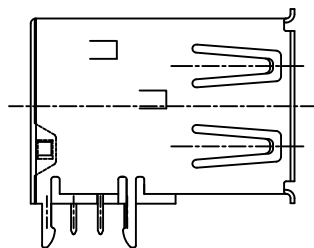
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

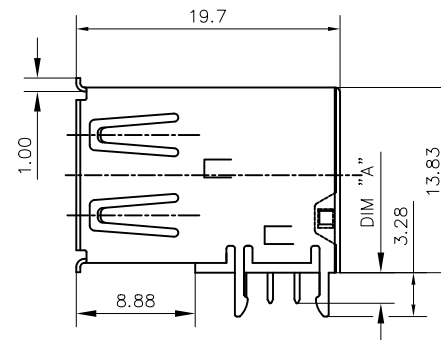
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

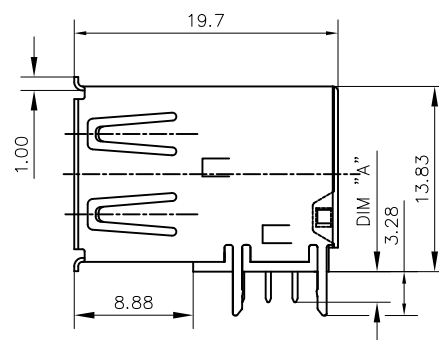


WITHOUT SENSOR CONTACT

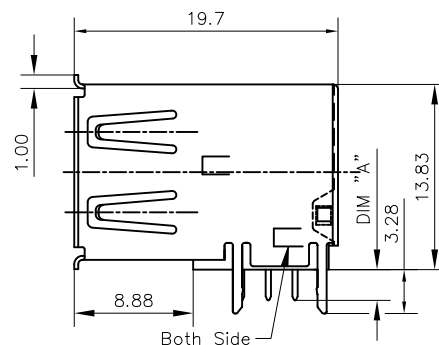


FOR 73725-X1X0B
HOLD DOWN STYLE "A"

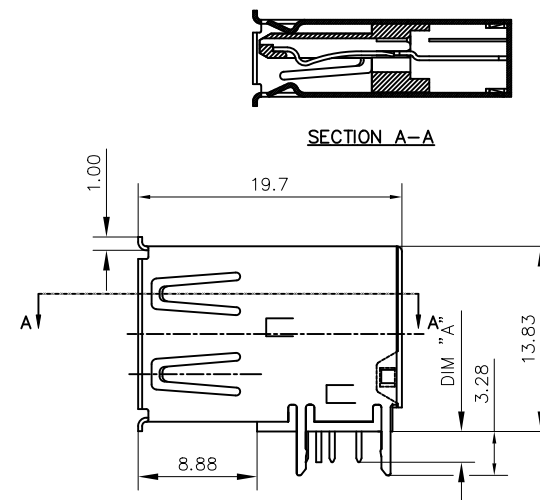
mat'l. code				surface ₁₂₃ /tolerance		projection		product family			
				ISO 1302 ✓ ISO 406 ISO 1101				HPL 511 USB 2.0			
ltr	ecn	no	dr	date		tolerances unless otherwise specified		title			
AJ						angles		linear		USB UP-RIGHT	
										RECEPT	
						.0±.30					
						.00±.20					
						0°±2'		.000±.10		scale 1:1	
				dr		PAMP		5/20/97		dwg no	
				eng		R Y LIU		5/20/97		sheet2 of 4	
				chr		R Y LIU		5/20/97		73725	
				app		JENN TSAO		5/20/97		A3	
sheet index		revision sheet									



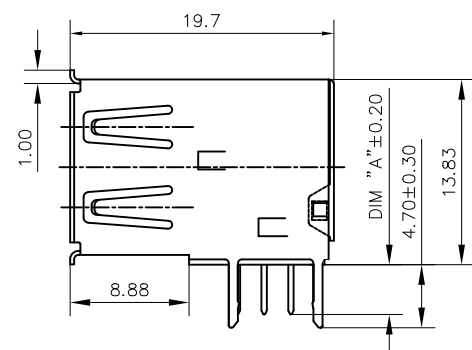
WITHOUT SENSOR CONTACT
FOR 73725-X1X0B
HOLD DOWN STYLE "B"



WITHOUT SENSOR CONTACT
FOR 73725-XXA0XLF ONLY
73725-XXB0XLF
HOLD DOWN STYLE "F"

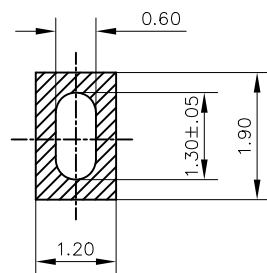


WITH SENSOR CONTACT
FOR 73725-X0X0B
HOLD DOWN STYLE "B"

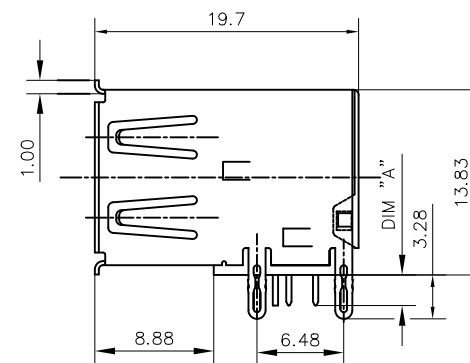


WITHOUT SENSOR CONTACT
FOR 73725-X191XLF
HOLD DOWN STYLE "D"

mat'l. code				surface ¹²³ /tolerance ISO 1302 ISO 406 ISO 1101				projection 		product family HPL 511 USB 2.0					
itr ecn no dr date				tolerances unless otherwise specified						title					
AJ				angles linear				mm		USB UP-RIGHT RECEPT					
				.0±.30											
				.00±.20											
				.00±.10											
				0°±2'				scale 1:1							
				dr PAMP 5/20/97				Amphenol FCi		dwg no sheet3 of 4 size					
				eng R Y LIU 5/20/97						73725 A3					
				chr R Y LIU 5/20/97											
				app JENN TSAO 5/20/97											
sheet index		revision sheet													



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WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

[illegible]